

Tyrone Camarero Specifications

Camarero- SDI200C3HE-26

Key Feature

5G Core and Edge, Telecom Micro Data Center, AI Inference and Machine Learning, Network Function Virtualization, Cloud Computing

- Dual Socket E (LGA-4677), 5th Gen Intel® Xeon® / 4th Gen Intel® Xeon® Scalable processors, Supports Intel Xeon CPU Max Series with high bandwidth memory (HBM)
- 32 DIMM slots/16 Channels, Max Memory (2DPC): Up to 8TB 5600MT/s ECC DDR5 RDIMM
- Configurable PCIe slot options up to 8 PCIe 5.0 x8 (6 FHFL+ 2 FHHL) or 4 PCIe 5.0 x16 (3 FHFL + 1 FHHL)
- Flexible networking options with 2 AIOM networking slots (OCP NIC 3.0 compatible)
- Up to 6x 2.5" hot-swap drive bays with options to support NVMe/SATA drives
- 6 heavy duty hot-swap fans with optimal fan speed control
- 2x 2000W Redundant Titanium (certification pending) Level power supplies



Processor/Cache		Front Panel	
Processor	Dual Socket E (LGA-4677), 4th Gen Intel® Xeon® Scalable processors, Intel Xeon CPU Max Series with high bandwidth memory (HBM), Up to 60C/120T; Up to 112.5MB Cache Note: Supports up to 350W TDP CPUs (Air Cooled)	LED Indicators	LAN1 activity, LAN2 activity, System information
Chipset		Buttons	Power On/Off
Chipset	Intel® C741 Chipset	Drive bays	
System Memory		Drive bays	6x 2.5" hot-swap NVMe/SATA drive bays (6x 2.5" NVMe hybrid), 2 M.2 NVMe OR 2 M.2 SATA3 M-Key, 2280/22110
Memory Capacity	Slot Count: 32 DIMM slots/16 Channels, Max Memory (2DPC): Up to 8TB 5600MT/s ECC DDR5 RDIMM	Power Supply	
Expansion Slots		Power Supply	2x 2000W Redundant Titanium (certification pending) Level power supplies
PCI-Express	6 PCIe 5.0 x16 FHFL slot(s), 2 PCIe 5.0 x16 FHHL slot(s) Note: If Slot 1 is configured as PCIe x16, Slot 2 will be disabled; If Slot 3 is configured as PCIe x16, Slot 4 will be disabled; If Slot 5 is configured as PCIe x16, Slot 6 will be disabled; (Optional) If Slot 7 is configured as PCIe x16, Slot 8 will be disabled.	Cooling System	
Integrated On-Board		Fans	6 Counter-rotating, Hot-swappable 6cm Fan(s)
SATA	SATA3 (6Gbps); RAID 0/1/5/10 support	Liquid Cooling	Direct to Chip (D2C) Cold Plate (optional)
Network	2x 25GbE SFP28 with Broadcom® BCM57414 (optional), 2x 100GbE QSFP28 with Broadcom® BCM57508 (optional), 2x 100GbE QSFP28 with Intel® E810-CAM2 (optional), 2x 100GbE QSFP28 with Mellanox® CX-6 DX (optional), 4x 10GbE SFP+ with Intel® X710-BM2 (optional), 4x 10GbE BaseT with Intel® X550 (optional)	Form Factor	
Add-on Options		Form Factor	2U Rackamount
Raid card	Optional	Dimensions	
Optical Drive	None	Dimensions	Height : 3.5" (88.9 mm), Width : 17.2" (436.88 mm), Depth : 22.6" (574 mm)
		<p>Email : Info@tyronesystems.com</p> <p>For more/current product information, Visit www.tyronesystems.com</p>	